

N-Ch MOSFET

General Description

The WSE9968A is the highest performance trench N-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSE9968A meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

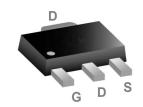
Product Summery

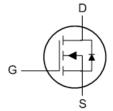
BVDSS	RDSON	ID
100V	75mΩ	4.4A

Applications

- High Frequency Point-of-Load Synchronous s Small power switching for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

SOT-89 Pin Configuration





Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	±20	V
I _D @T _A =25℃	Continuous Drain Current, V _{GS} @ 10V ¹	4.4	Α
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ 10V ¹	3.5	А
I _{DM}	Pulsed Drain Current ²	16	А
EAS	Single Pulse Avalanche Energy ³	12	mJ
I _{AS}	Avalanche Current	7.0	Α
P _D @T _A =25℃	Total Power Dissipation ³	3.5	W
T _{STG}	Storage Temperature Range	-55 to 150	$^{\circ}$
TJ	Operating Junction Temperature Range -55 to 150		$^{\circ}$

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-ambient ¹		85	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case ¹		35	°C/W



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	100			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25℃ , I _D =1mA		0.098		V/°C
D	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =4A		75	95	mΩ
R _{DS(ON)}		V _{GS} =4.5V , I _D =3.5A		80	120	mΩ
V _{GS(th)}	Gate Threshold Voltage)/ -\/ -250\	1.0	2.0	3.0	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=250uA$		-4.57		mV/℃
		V_{DS} =80V , V_{GS} =0V , T_J =25 $^{\circ}$ C			1	- uA
I _{DSS}	Drain-Source Leakage Current	V _{DS} =80V , V _{GS} =0V , T _J =55℃			5	
I _{GSS}	Gate-Source Leakage Current	V_{GS} = $\pm 20V$, V_{DS} = $0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =2A		20		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		2.5	4	Ω
Q_g	Total Gate Charge (10V)			16	22	
Q_{gs}	Gate-Source Charge	V _{DS} =80V , V _{GS} =10V , I _D =4A		2.5	4.2	nC
Q _{gd}	Gate-Drain Charge			3	4.5	
T _{d(on)}	Turn-On Delay Time			11	20	
Tr	Rise Time	V_{DD} =50V , V_{GS} =10V , R_{G} =6 Ω I_{D} =1A , R_{L} =30 Ω .		6	11	200
T _{d(off)}	Turn-Off Delay Time			27	49	ns
T _f	Fall Time			5	10	
Ciss	Input Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		760	980	
C _{oss}	Output Capacitance			46		pF
C _{rss}	Reverse Transfer Capacitance			26		

Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy ⁵	V _{DD} =25V , L=0.5mH , I _{AS} =4A	12			mJ

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I _S	Continuous Source Current ^{1,6}	V _G =V _D =0V , Force Current			3.0	Α
I _{SM}	Pulsed Source Current ^{2,6}				16	Α
V_{SD}	Diode Forward Voltage ²	V_{GS} =0V , I_S =1A , T_J =25 $^{\circ}$ C			1.2	V
t _{rr}	Reverse Recovery Time	lF=3A,dl/dt=100A/μs , Tյ=25℃		27		nS
Q _{rr}	Reverse Recovery Charge			36		nC

Note:

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%
- 3.The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V,L=0.5mH,I_{AS}=4A
- 5.The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



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Typical Characteristics

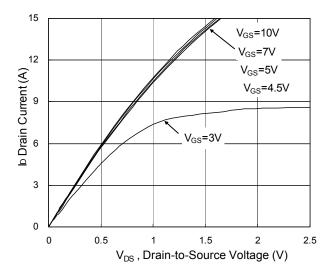


Fig.1 Typical Output Characteristics

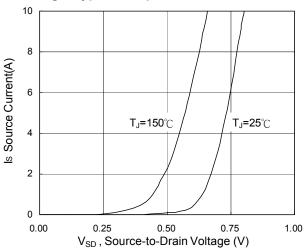


Fig.3 Forward Characteristics Of Reverse

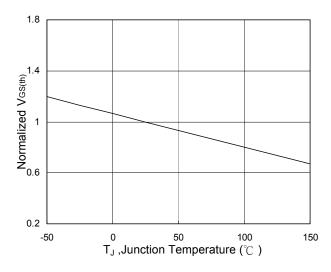


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

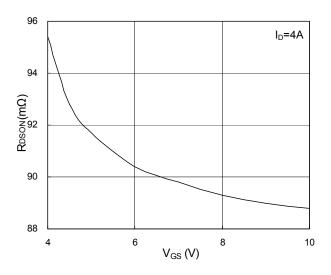


Fig.2 On-Resistance vs. Gate-Source

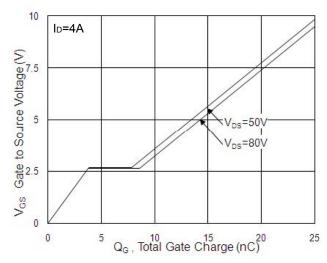


Fig.4 Gate-Charge Characteristics

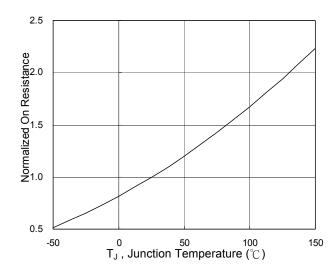
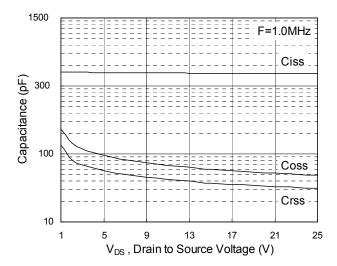


Fig.6 Normalized R_{DSON} vs. T_J





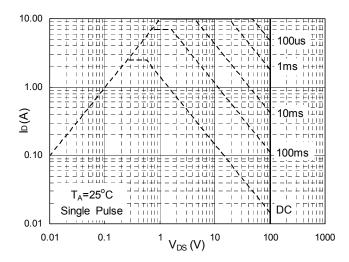


Fig.7 Capacitance

Fig.8 Safe Operating Area

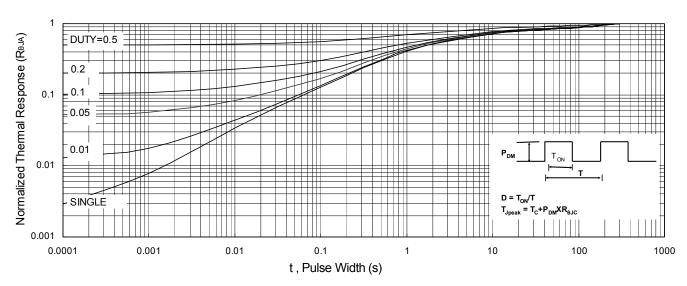


Fig.9 Normalized Maximum Transient Thermal Impedance

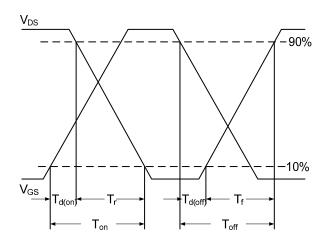


Fig.10 Switching Time Waveform

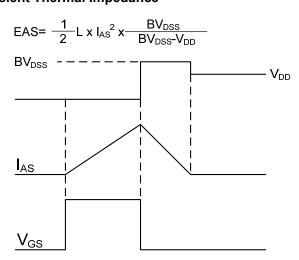


Fig.11 Unclamped Inductive Switching Waveform



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